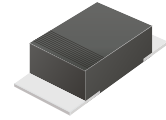


## CSFM101-G Thru. CSFM105-G

Reverse Voltage: 50 to 600 Volts

Forward Current: 1.0 Amp

RoHS Device

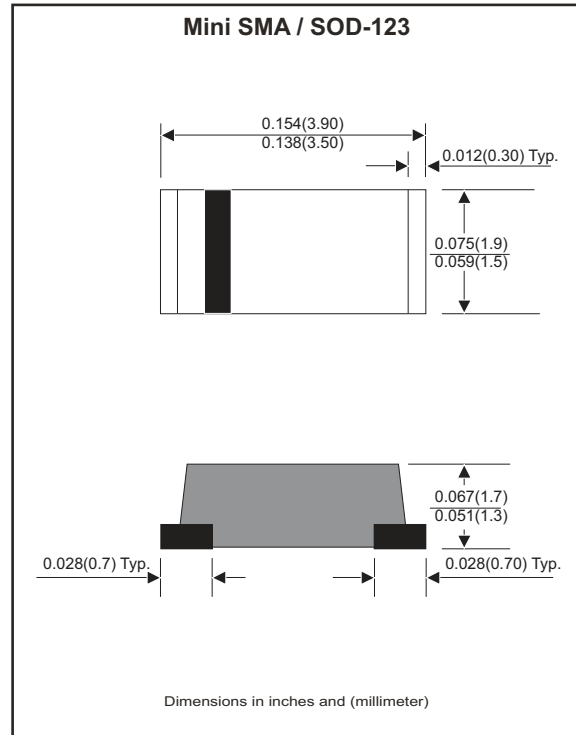


### Features

- Batch process design,excellent power dissipation offers better reverse leakage current and thermal resistance.
- Low profile surface mounted application in order to optimize board space.
- Tiny plastic SMD package.
- Super fast recovery time for switching mode application.
- High current capability.
- High surge current capability.
- Glass passivated chip junction.

### Mechanical data

- Epoxy: UL 94-V0 rated flame retardant.
- Case: Molded plastic, JEDEC SOD-123/Mini SMA.
- Terminals: Solderable per MIL-STD-750, method 2026.
- Polarity: Indicated by cathode band.
- Weight: 0.018 grams approx.



### Maximum Ratings (at TA=25°C unless otherwise noted)

Parameter	Conditions	Symbol	CSFM 101-G	CSFM 102-G	CSFM 103-G	CSFM 104-G	CSFM 105-G	Unit
Repetitive peak reverse voltage		$V_{RRM}$	50	100	200	400	600	V
Continuous reverse voltage		$V_{DC}$	50	100	200	400	600	V
RMS voltage		$V_{RMS}$	35	70	140	280	420	V
Max. forward rectified current	Ambient temperature=50°C	$I_o$	1.0					A
Maximum Instantaneous forward voltage at $I_F=1.0A$		$V_F$	0.95		1.25	1.70		V
Forward surge current	8.3ms single half sine-wave superimposed on rated load (JEDEC method)	$I_{FSM}$	25					A
Max. Reverse recovery time	$I_F=0.5A$ , $I_R=1.0A$ $I_{RR}=0.25A$	$T_{rr}$	35					nS
Max.Reverse current	$V_R=V_{RRM}$ $T_J=@25^\circ C$ $V_R=V_{RRM}$ $T_J=@100^\circ C$	$I_R$	5.0 100					$\mu A$
Typ. Thermal resistance	Junction to ambient	$R_{\theta JA}$	42					°C/W
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	$C_J$	10					pF
Operating junction temperature		$T_J$	-55 to +150					°C
Storage temperature range		$T_{STG}$	-65 to +175					°C

## Rating and Characteristic Curves (CSFM101-G Thru. CSFM105-G)

Fig.1 - Typical Forward Characteristics

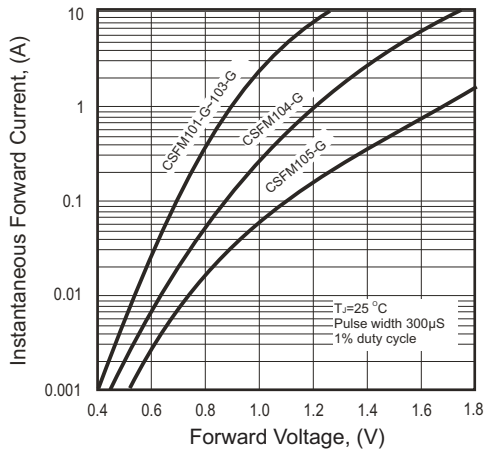


Fig.2 - Typical Forward Current Derating Curve

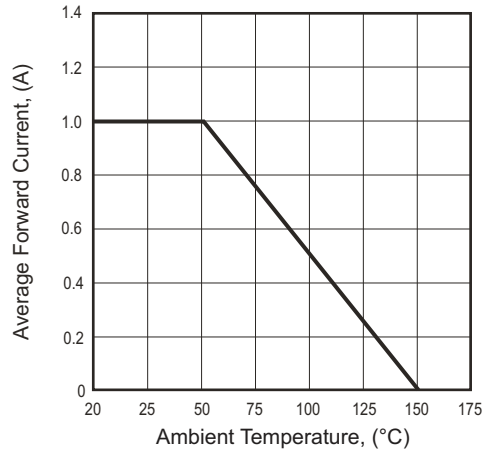
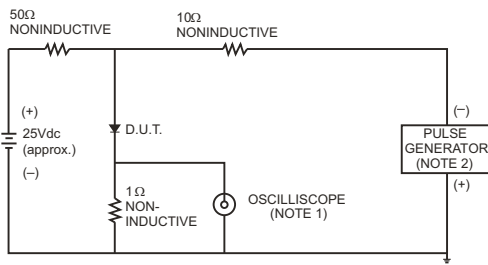


Fig.3 - Test Circuit Diagram and Reverse Recovery Time Characteristics



NOTES: 1. Rise Time= 7ns max., Input Impedance= 1 megohm, 22pF.  
2. Rise Time= 10ns max., Source Impedance= 50 ohms.

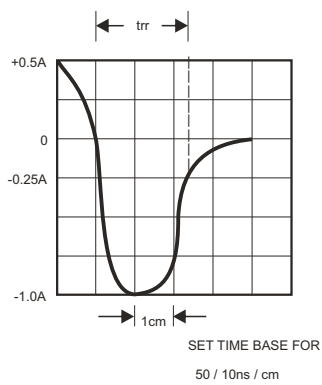


Fig.4 - Non-repetitive Forward Surge Current

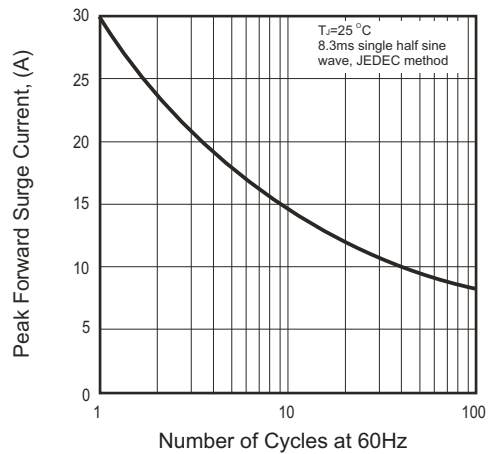
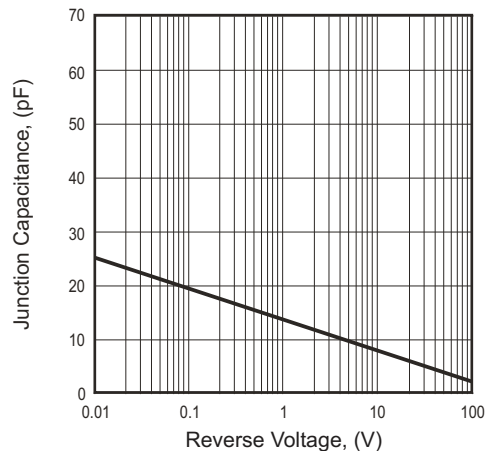
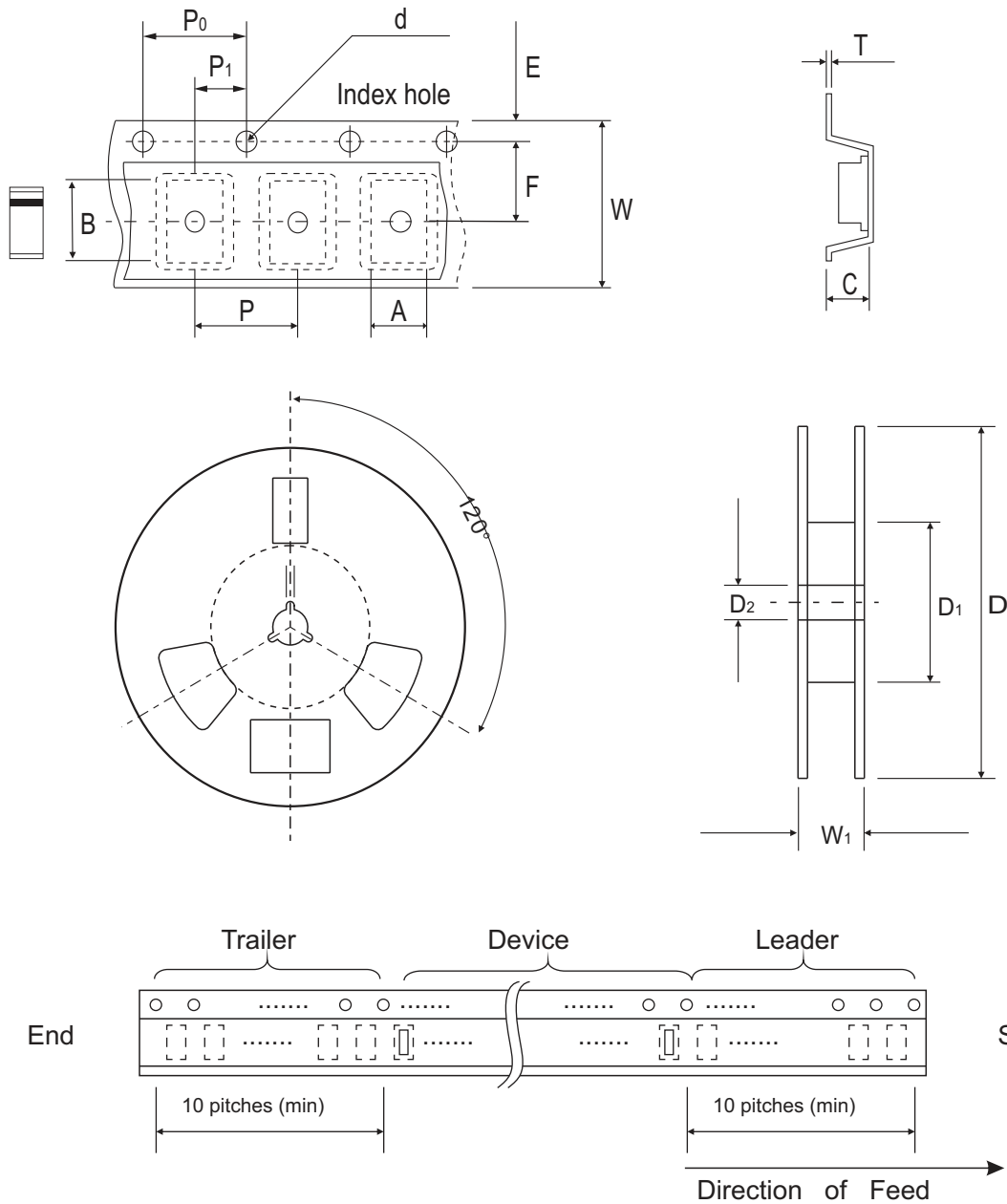


Fig.5 - Typical Junction Capacitance



## Reel Taping Specification



	SYMBOL	A	B	C	d	D	D1	D2
Mini-SMA/SOD-123	(mm)	1.90 ± 0.10	3.90 ± 0.10	1.68 ± 0.10	1.50 ± 0.10	178 ± 2.00	62.0 MIN.	13.0 ± 0.50
	(inch)	0.075 ± 0.04	0.154 ± 0.04	0.066 ± 0.04	0.059 ± 0.004	7.00 ± 0.079	2.440 MIN.	0.512 ± 0.020

	SYMBOL	E	F	P	P0	P1	T	W	W1
Mini-SMA/SOD-123	(mm)	1.75 ± 0.10	3.50 ± 0.10	4.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.10	0.23 ± 0.10	8.00 ± 0.30	11.40 ± 1.0
	(inch)	0.069 ± 0.004	0.138 ± 0.004	0.157 ± 0.004	0.157 ± 0.004	0.079 ± 0.004	0.009 ± 0.004	0.315 ± 0.012	0.449 ± 0.004

## Marking Code

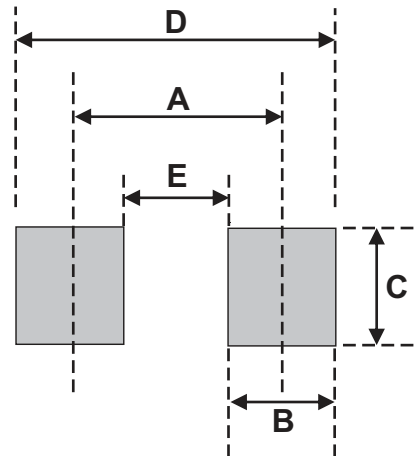
Part Number	Marking Code
CSFM101-G	S1
CSFM102-G	S2
CSFM103-G	S3
CSFM104-G	S6
CSFM105-G	S8



XX = Product type marking code

## Suggested PAD Layout

SIZE	Mini-SMA/SOD-123	
	(mm)	(inch)
A	3.30	0.130
B	1.40	0.055
C	1.90	0.075
D	4.70	0.185
E	1.90	0.075



## Standard Packaging

Case Type	Qty per Reel	Reel Size
	(Pcs)	(inch)
Mini-SMA/SOD-123	2500	7